

RJE0625JPV

P Channel Thermal FET Series Power Switching

R07DS1529EJ0100
Rev.1.00
Mar 30, 2023

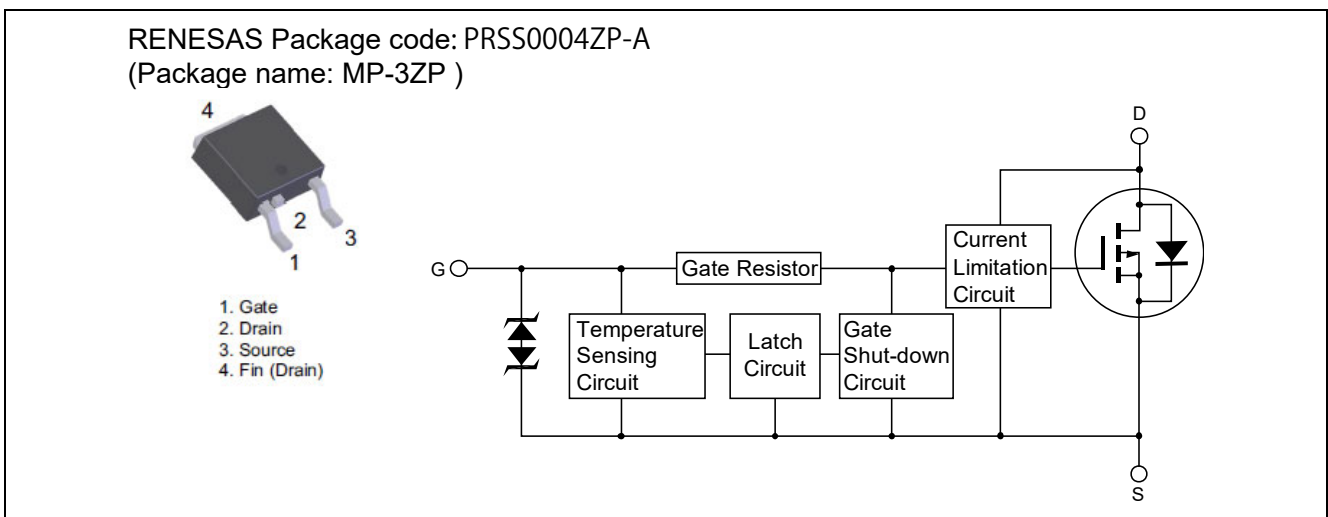
Description

This FET has the over temperature shut-down capability sensing to the junction temperature. This FET has the built-in over temperature shut-down circuit in the gate area. And this circuit operation to shut-down the gate voltage in case of high junction temperature like applying over power consumption, over current etc..

Features

- Logic level operation (–6 V Gate drive).
- Built-in the over temperature shut-down circuit.
- High endurance capability against to the short circuit.
- Latch type shut down operation (need 0 voltage recovery).
- Built-in the current limitation circuit.
- AEC-Q101 Rev-E Compliant

Outline



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	–60	V
Gate to source voltage	V _{GSS}	–16	V
Gate to source voltage	V _{GSS}	2.5	V
Drain current	I _D ^{Note3}	–17	A
Body-drain diode reverse drain current	I _{DR}	–17	A
Avalanche current	I _{AF} ^{Note 2}	–8	A
Avalanche energy	E _{AR} ^{Note 2}	274	mJ
Channel dissipation	P _{ch} ^{Note 1}	50	W
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	–55~+150	°C

- Notes: 1. Value at Tc = 25°C
2. T_{ch} = 25°C, R_g ≥ 50 Ω
3. It provides by the current limitation lower bound value.

Typical Operation Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Input voltage	V _{IH}	-3.5	—	—	V	
	V _{IL}	—	—	-1.2	V	
Input current (Gate non shut down)	I _{IH1}	—	—	-100	μA	V _i = -8 V, V _{DS} = 0
	I _{IH2}	—	—	-50	μA	V _i = -3.5 V, V _{DS} = 0
	I _{IL}	—	—	-1	μA	V _i = -1.2 V, V _{DS} = 0
Input current (Gate shut down)	I _{IH(sd)1}	—	-0.8	—	mA	V _i = -8 V, V _{DS} = 0
	I _{IH(sd)2}	—	-0.35	—	mA	V _i = -3.5 V, V _{DS} = 0
Shut down temperature	T _{sd}	—	175	—	°C	Channel temperature (dv/dt V _{GS} ≥ 500 V/ms)
Gate operation voltage	V _{op}	-3.5	—	-12	V	
Drain current (Current limitation value)	I _{D limit}	-17	—	—	A	V _{GS} = -12 V, V _{DS} = -10 V ^{Note 4}

Notes; 4. Pulse test

Electrical Characteristics

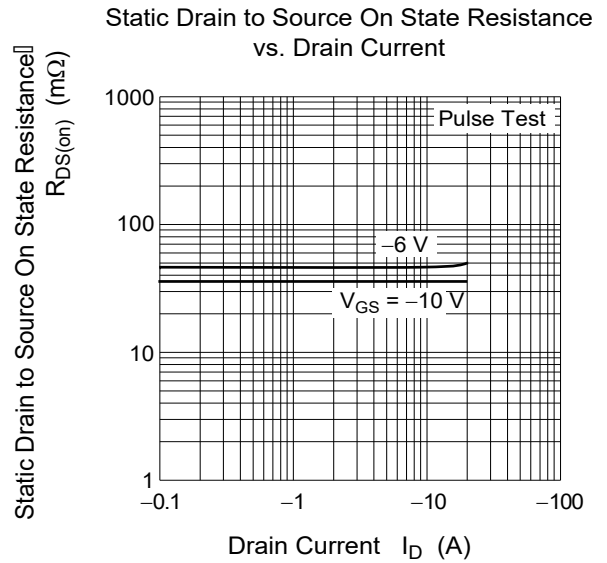
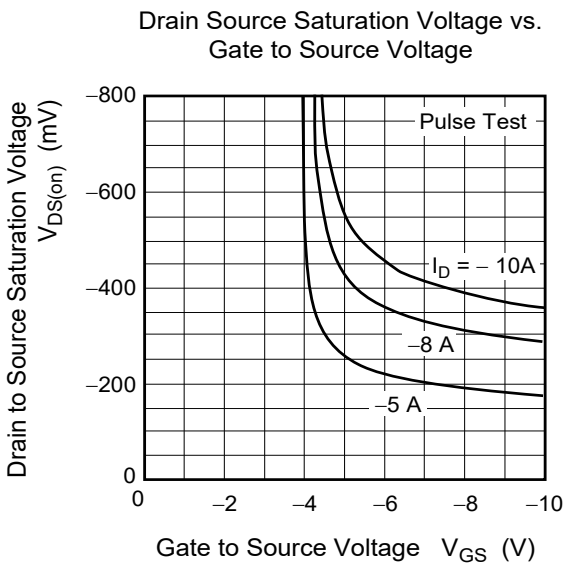
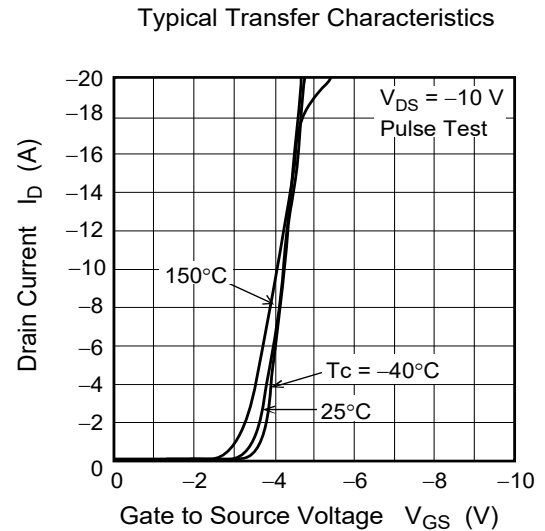
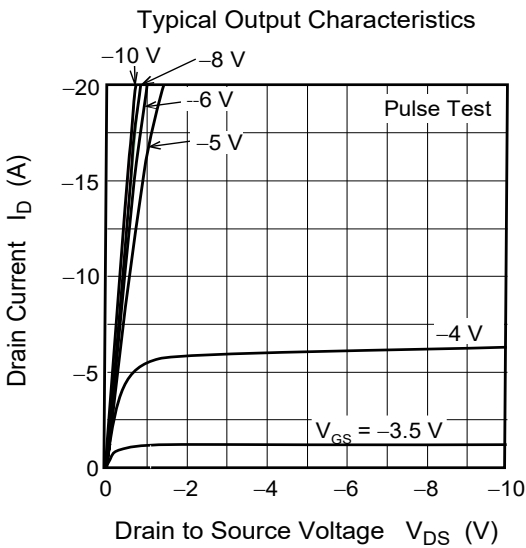
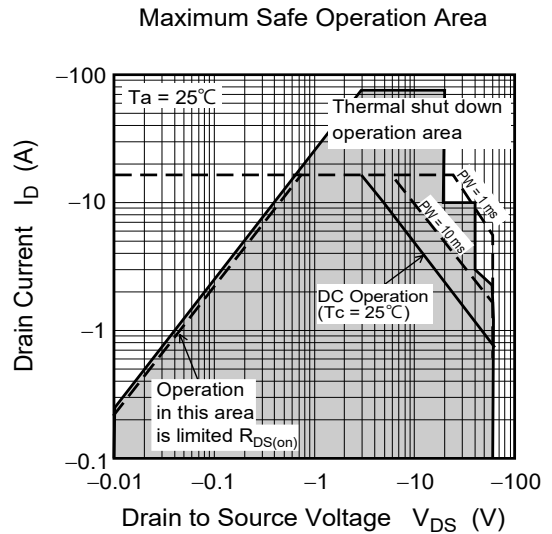
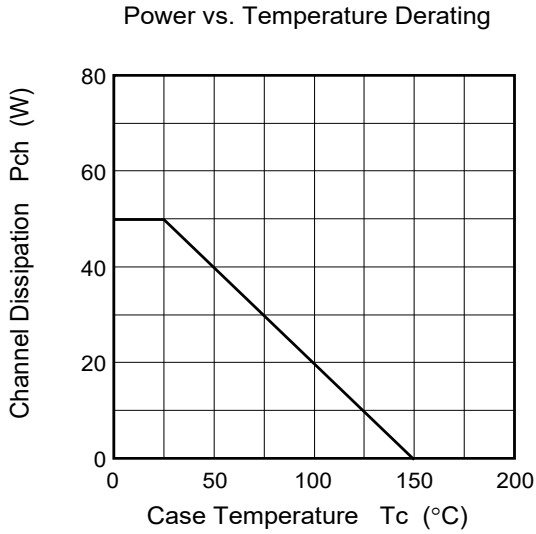
(Ta = 25°C)

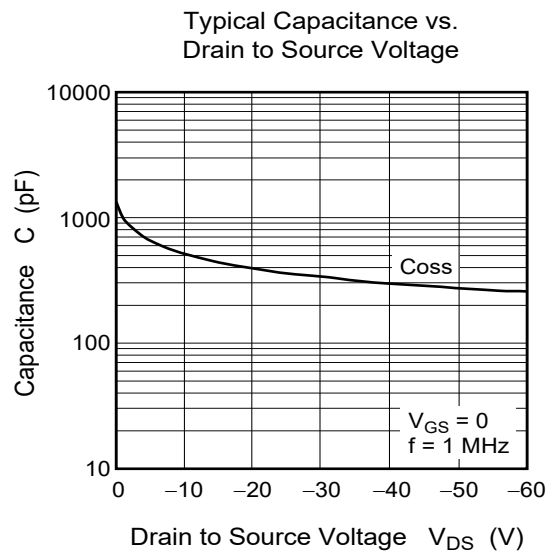
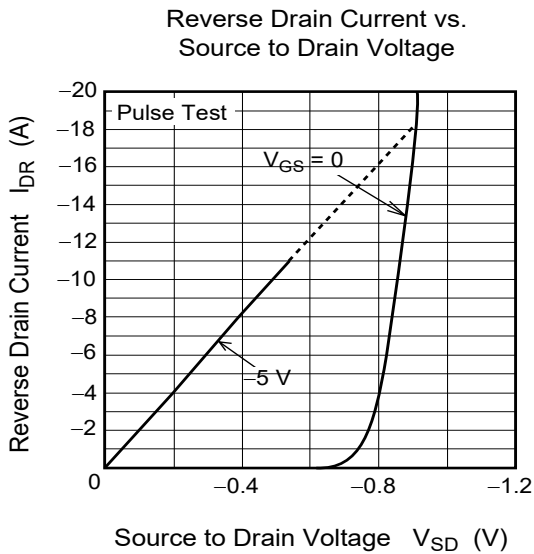
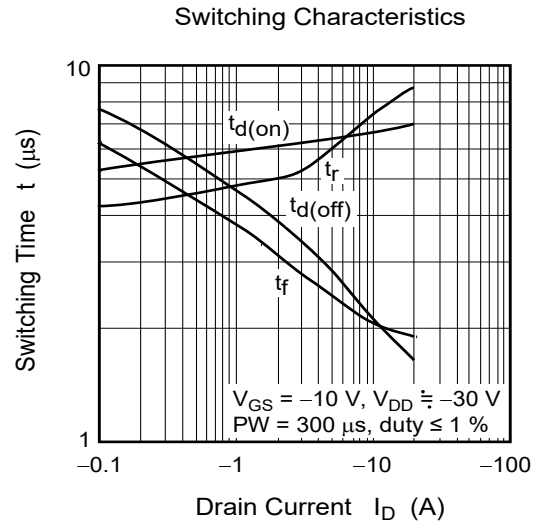
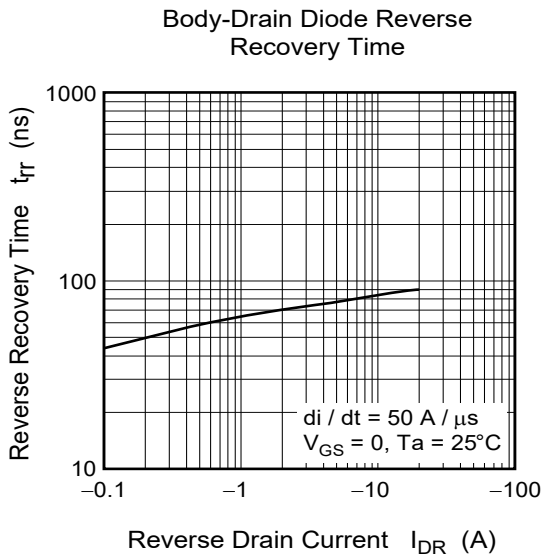
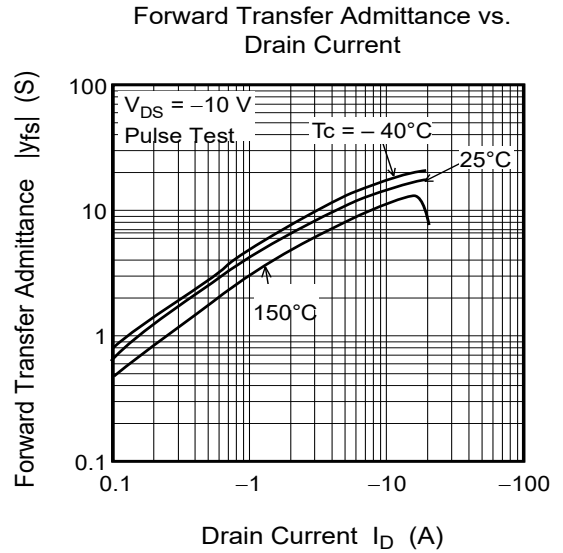
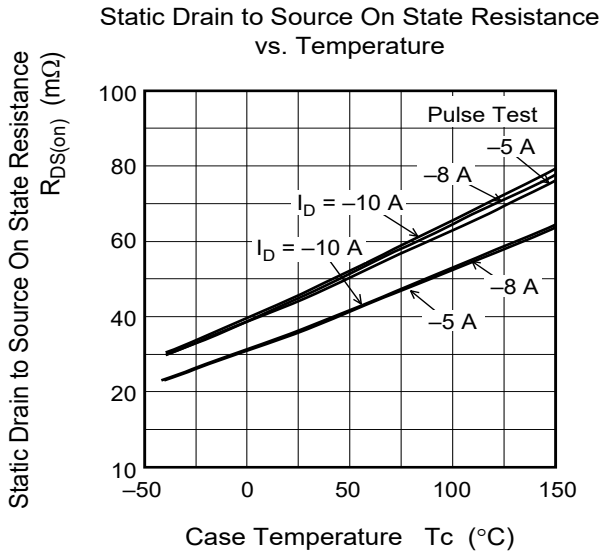
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain current	I _{D1}	—	—	-12	A	V _{GS} = -3.5 V, V _{DS} = -10 V ^{Note 5}
	I _{D2}	—	—	-10	mA	V _{GS} = -1.2 V, V _{DS} = -10 V
	I _{D3}	-17	—	—	A	V _{GS} = -12 V, V _{DS} = -10 V ^{Note 5}
Drain to source breakdown voltage	V _{(BR)DSS}	-60	—	—	V	I _D = -10 mA, V _{GS} = 0
Gate to source breakdown voltage	V _{(BR)GSS1}	-16	—	—	V	I _G = -800 μA, V _{DS} = 0
	V _{(BR)GSS2}	2.5	—	—	V	I _G = 100 μA, V _{DS} = 0
Gate to source leak current	I _{GSS1}	—	—	-100	μA	V _{GS} = -8 V, V _{DS} = 0
	I _{GSS2}	—	—	-50	μA	V _{GS} = -3.5 V, V _{DS} = 0
	I _{GSS3}	—	—	-1	μA	V _{GS} = -1.2 V, V _{DS} = 0
	I _{GSS4}	—	—	100	μA	V _{GS} = 2.4 V, V _{DS} = 0
Input current (shut down)	I _{GS(OP)1}	—	-0.8	—	mA	V _{GS} = -8 V, V _{DS} = 0
	I _{GS(OP)2}	—	-0.35	—	mA	V _{GS} = -3.5 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	-10	μA	V _{DS} = -60 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	-2.2	—	-3.4	V	V _{DS} = -10 V, I _D = -1 mA
Forward transfer admittance	y _{fs}	8.4	14.9	—	S	I _D = -10 A, V _{DS} = -10 V ^{Note 5}
Static drain to source on state resistance	R _{DS(on)1}	—	46.6	61	mΩ	I _D = -10 A, V _{GS} = -6 V ^{Note 5}
	R _{DS(on)2}	—	36.8	45	mΩ	I _D = -10 A, V _{GS} = -10 V ^{Note 5}
Output capacitance	C _{oss}	—	515	—	pF	V _{DS} = -10 V, V _{GS} = 0, f = 1MHz
Turn-on delay time	t _{d(on)}	—	6.48	—	μs	V _{GS} = -10 V, I _D = -10 A, R _L = 3 Ω
Rise time	t _r	—	7.09	—	μs	
Turn-off delay time	t _{d(off)}	—	2.06	—	μs	
Fall time	t _f	—	2.07	—	μs	
Body-drain diode forward voltage	V _{DF}	—	-0.9	—	V	I _F = -17 A, V _{GS} = 0
Body-drain diode reverse recovery time	t _{rr}	—	91.1	—	ns	I _F = -17 A, V _{GS} = 0 di _F /dt = 50 A/μs
Over load shut down operation time ^{Note 6}	t _{os1}	—	1.7	—	ms	V _{GS} = -6 V, V _{DD} = -16 V

Notes: 5. Pulse test

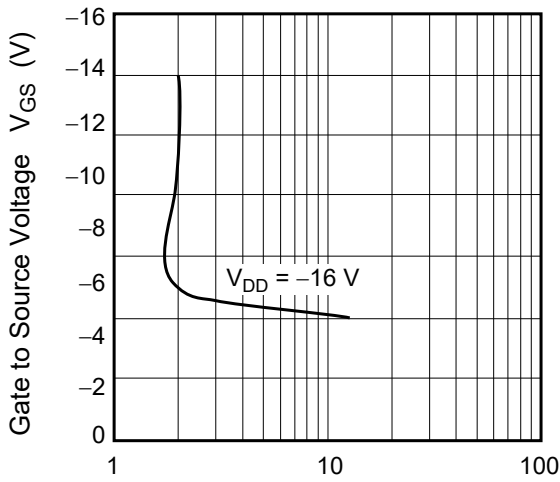
6. Including the junction temperature rise of the over loaded condition.

Main Characteristics



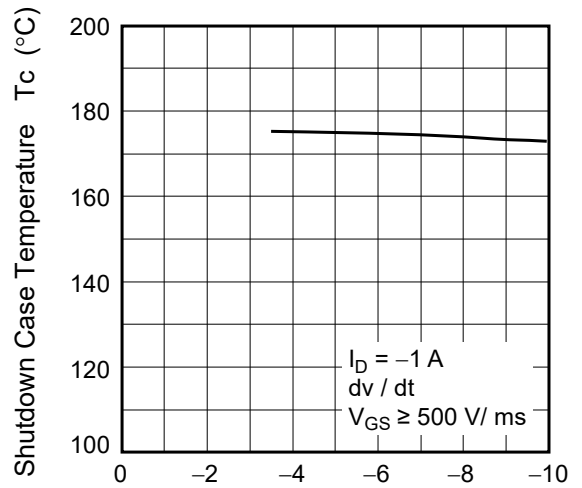


Gate to Source Voltage vs. Shutdown Time of Load-Short Test



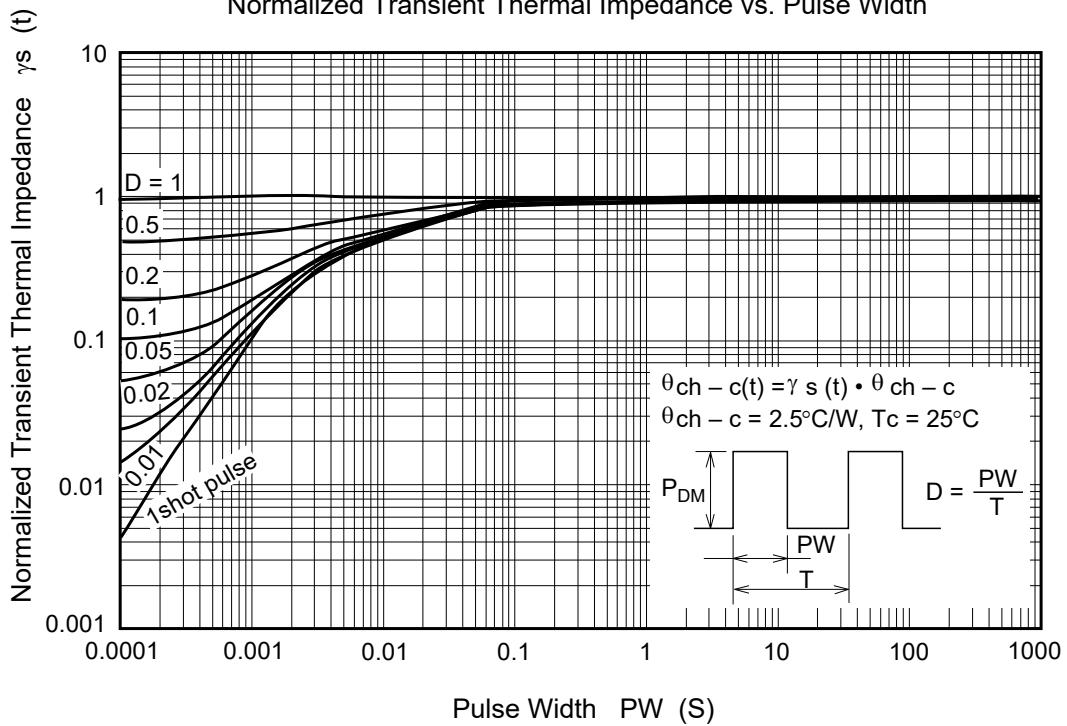
Shutdown Time of Load-Short Test P_w (ms)

Shutdown Case Temperature vs. Gate to Source Voltage

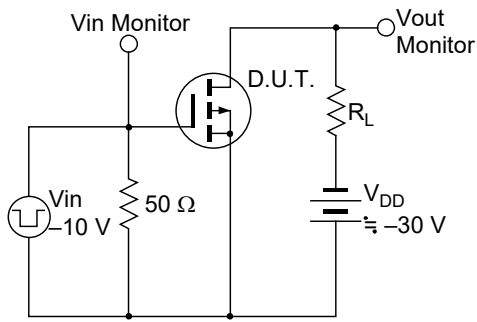


Gate to Source Voltage V_{GS} (V)

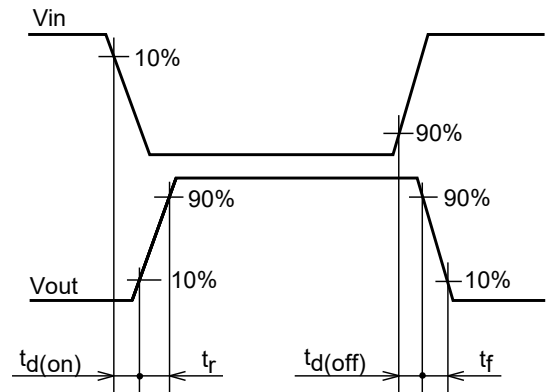
Normalized Transient Thermal Impedance vs. Pulse Width



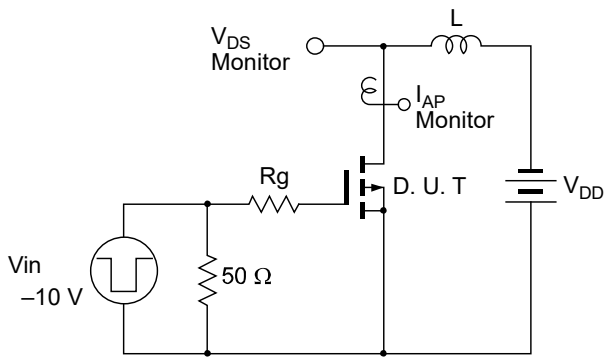
Switching Time Test Circuit



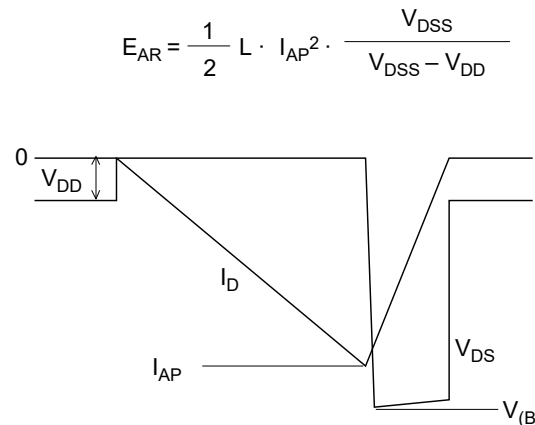
Waveform



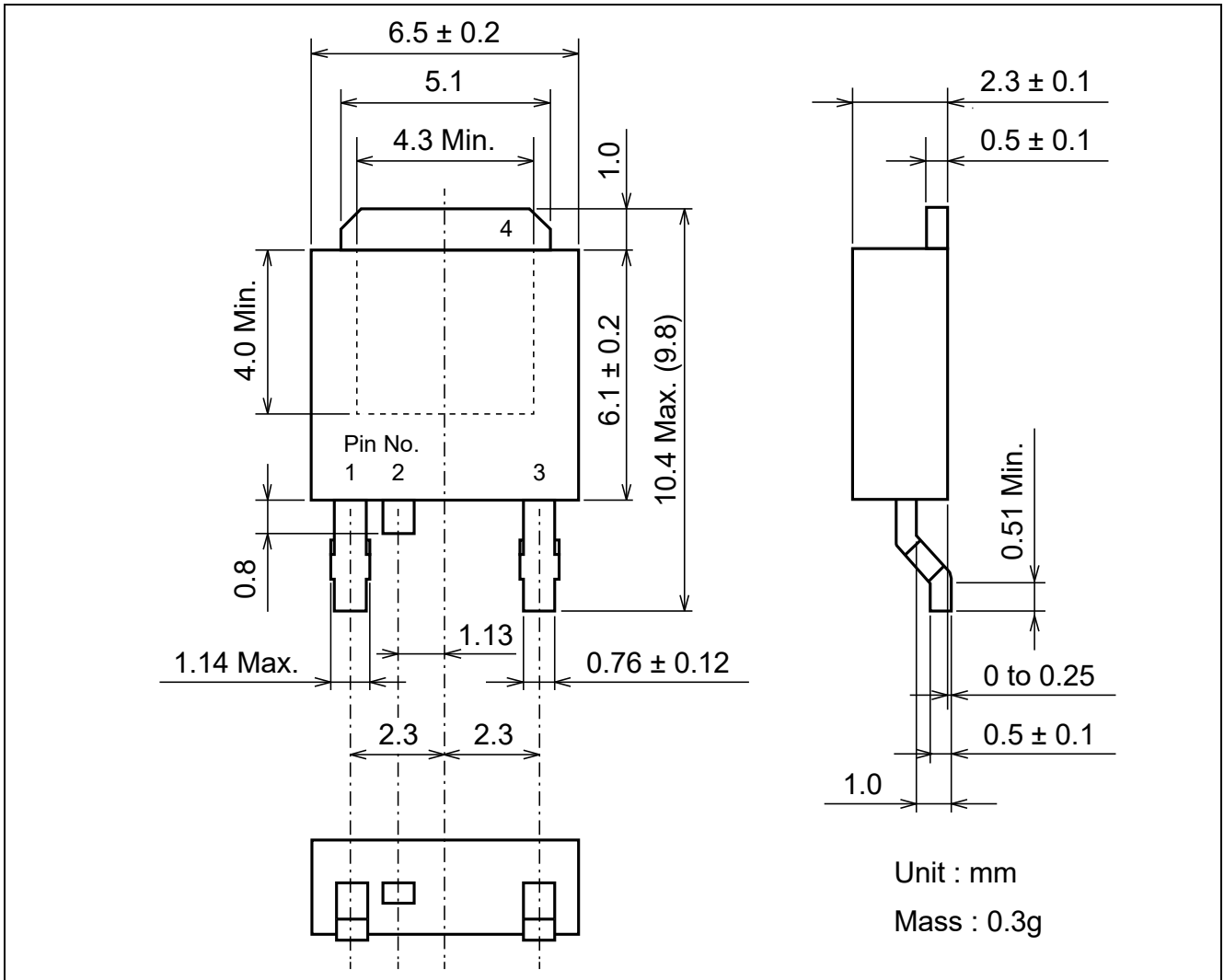
Avalanche Test Circuit



Avalanche Waveform



Package Dimensions



Ordering Information

Part No.	Quantity	Shipping Container
RJE0625JPV-00-Q7	2500 pcs	Taping (Sinistrorse)

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(Rev.5.0-1 October 2020)

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